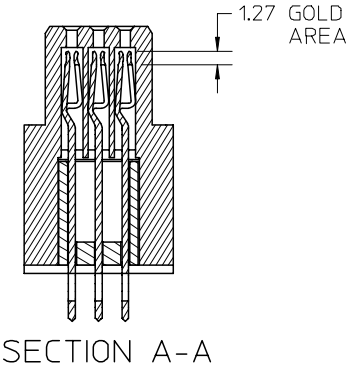
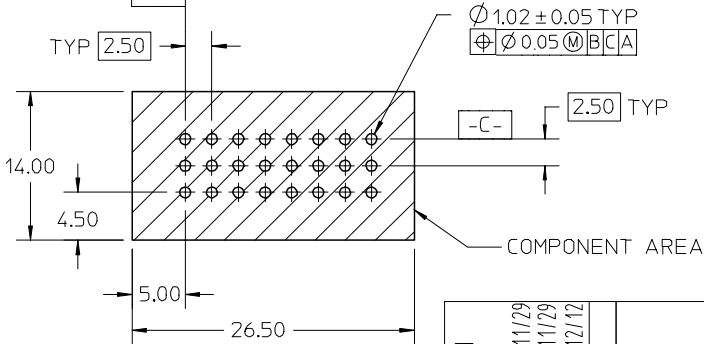
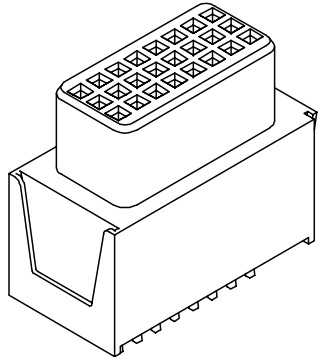


- NOTES:
- HOUSING MATERIAL: LCP, 30% GLASS FILLED, UL94V-0, BLACK
 TERMINAL MATERIAL: COPPER ALLOY - C7026 (TMOS)
 BLADE MATERIAL: COPPER ALLOY - C110
 - FINISH: SELECT GOLD: 30 MI MIN
 SELECT TIN: 150 / 250 MI
 BOTH OVER NICKEL: 50 MI MIN
 - PRODUCT SPECIFICATION: PS-45424-001.
 - PACKAGING SPECIFICATION: ES-45484-999
 - PRODUCT AND/OR PROCESS CHANGES MUST BE APPROVED BY MOLEX ENGINEERING PRIOR TO IMPLEMENTATION.
 - DIMENSIONS GIVEN ACROSS CENTERLINES ARE SYMMETRICAL ABOUT THOSE CENTERLINES WITHIN HALF THE TOTAL TOLERANCE.
 - TERMINAL RETENTION IN HOUSING: 2.5 LBS MIN.
 - THIS MODULE MUST INTERLOCK WITH ALL STANDARD MOLEX POWER DOCK MODULES.
 - PART IS RoHS COMPLIANT. SEE ES-45484-999 FOR LABEL REQUIREMENTS.



PCB LAYOUT: COMPONENT SIDE
 PCB TOLERANCE: ±0.05
 PCB THKNESS: 2.36

STANDARDIZATION EC NO: UCP2005-1675 DRWN:KSAMIEC 2005/11/29 CHKD:KSAMIEC 2005/11/29 APPR:APATEL 2005/12/12	DESCRIPTION	REV
		B

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± 0.15	± ---
1 PLACE ± 0.25	± ---
ANGULAR ± 1/2°	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
SCHAFER	2005/2/9
CHECKED BY	DATE
SAMIEC	2005/2/10
APPROVED BY	DATE
MARGULIS	2005/2/11
MATERIAL NO.	455310001
SIZE	A

SCALE 1.5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE POWER DOCK MODULE SIGNAL SOCKET 24 PIN VERTICAL CPI		
MOLEX INCORPORATED		
MATERIAL NO. 455310001	DOCUMENT NO. SD-45531-001	SHEET NO. 1 OF 1
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